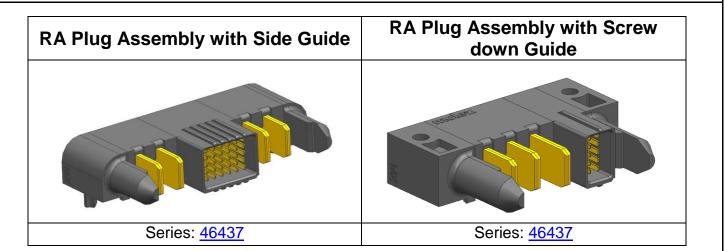
EXTREME TEN60POWER[™] Board-To-Board CONNECTOR SYSTEM

| RA Receptacle Assembly with Top Guide | RA Receptacle Assembly with Side Guide |
|------------------------------------------|-------------------------------------------|
| | |
| Series: <u>46436</u> | Series: <u>46436</u> |

| RA Receptacle Assembly with Screw down Guide | RA Plug Assembly with Top Guide |
|-------------------------------------------------|---------------------------------|
| | |
| Series: <u>46436</u> | Series: <u>46437</u> |

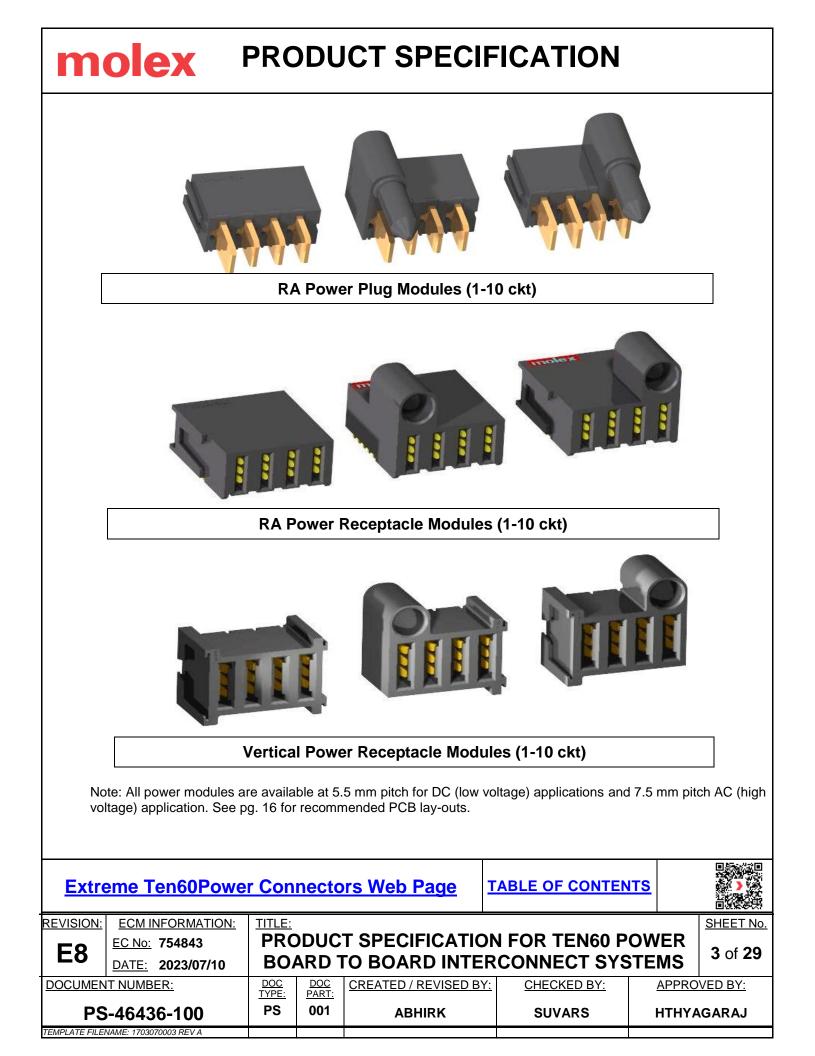
| Extreme Ten60Power Connectors Web Page TABLE OF CONTENTS | | | | | | | | |
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| E 8 | <u>EC No:</u> 754843 <u>DATE:</u> 2023/07/10 | PRODUCT SPECIFICATION FOR TEN60 POWER BOARD TO BOARD INTERCONNECT SYSTEMS | | | | | | |
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| PS-46436-100 | | <u>TYPE:</u> PS | 001 | ABHIRK | SUVARS | HTHYA | GARAJ | |
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| Vertical Receptacle Assembly with Top Guide | Vertical Receptacle Assembly with Side Guide |
|------------------------------------------------|-------------------------------------------------|
| | |
| Series: <u>46562</u> | Series: <u>46562</u> |

| Vertical Receptacle Assembly | Vertical Plug Assembly |
|------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| HI DA WARA A | Contraction of the second seco |
| Series: <u>76541</u> | Series: <u>76546</u> |

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| DOCUMEN | DOCUMENT NUMBER: | | | CREATED / REVISED BY | : CHECKED BY: | <u>APPRO</u> | VED BY: | |
| PS-46436-100 | | <u>TYPE:</u> PS | <u>PART:</u> 001 | ABHIRK | SUVARS | HTHYA | GARAJ | |
| TEMPLATE FILE | NAME: 1703070003 REV A | | | | | | | |



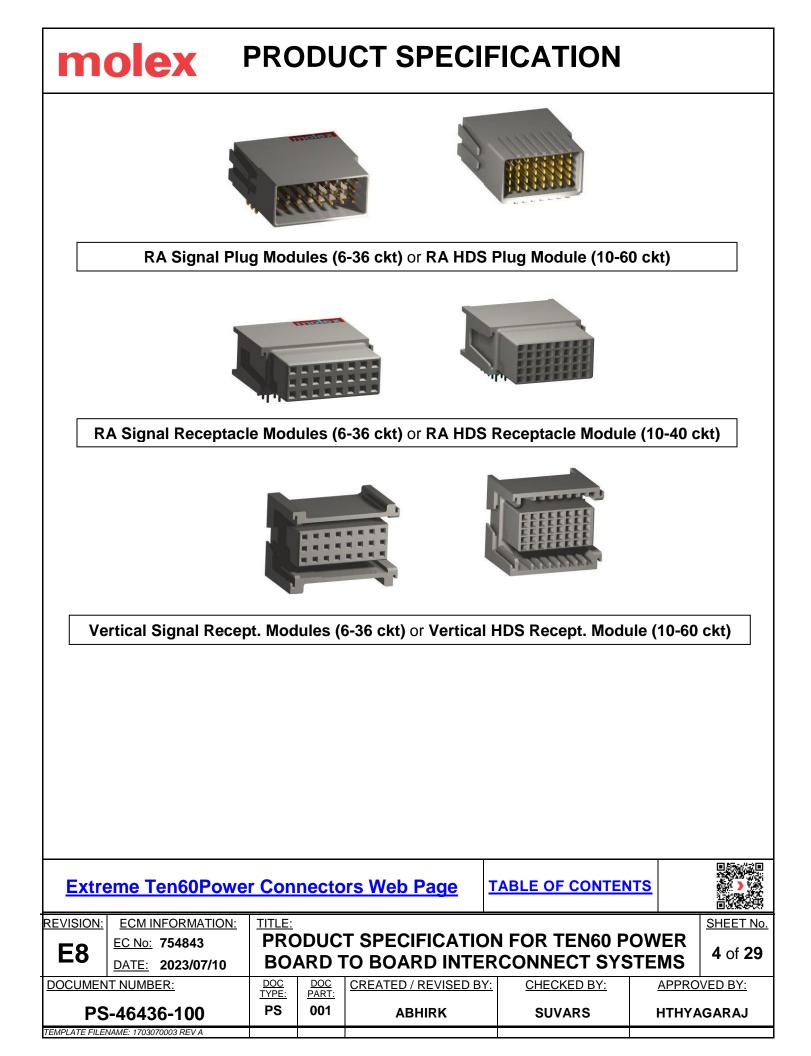


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| TEMPI ATE EII EI | NAME: 1703070003 REV A | 1 | | | | | |

P<u>AGE</u>

molex

PRODUCT SPECIFICATION

1.0 SCOPE

The specification covers the performance requirements and test methods of Ten60Power and signal modular board to board interconnect systems.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER (S)

This specification covers following board to board configuration Right Angle (RA) Plug assembly mated to RA Receptacle assembly (Coplanar configuration)

| 46436-XXXX | RA Receptacle Side Assembly | | | |
|------------|-----------------------------|--|--|--|
| 46437-XXXX | RA Plug Side Assembly | | | |

Right Angle (RA) Plug assembly mated to Vertical Receptacle assembly (Backplane configuration)

| 46562-XXXX | Vertical Receptacle Side Assembly |
|------------|-----------------------------------|
| 46437-XXXX | RA Plug Side Assembly |

Vertical Plug Assy mated to Vertical Receptacle Assy (Mezzanine configuration)

| 76541-XXXX | Vertical Receptacle Side Assembly |
|------------|-----------------------------------|
| 76546-XXXX | Vertical Plug Side Assembly |

2.2 DIMENSIONS, MATERIALS, PLATINGS

Dimensions: See individual sales drawings. Plating: Gold on mating surfaces and tin on PC tail with nickel under-plating overall.

2.3 ENVIRONMENTAL CONFORMANCE

To find product compliance information:

- a. Go to molex.com
- b. Enter the part number in the search field.
- c. At the bottom of the page go to "Environmental" to see compliance status.

| Extre | eme Ten60Powe | TABLE OF CONTEN | ITS | | | | |
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| PS-46436-100 | | <u>TYPE:</u> PS | <u>PART:</u> 001 | ABHIRK | SUVARS | HTHY | GARAJ |
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2.4 SAFETY AGENCY LISTINGS

2.4.1

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^{US} File Number*: LR-19980 A 000 Class 6233-81

CSA approval meets following standards/test procedures:

- a) CSA std. C22.2 No. 182.3-M1987
- b) UL-1977

* - "C" and "US" mark adjacent to CSA signifies that the product has been evaluated to the applicable CSA and ANSI/UL standards, for use in Canada and US respectively.

| CSA | CSA |
|---------------------------------------|--------------------------------------|
| NON-current interruption | Current interruption |
| 2.5 Amps @ 250V for Legacy Signal ckt | 2.5 Amp at 28V for Legacy Signal ckt |
| 4.5 Amps @ 75V for HDS Signal ckt | 4.5 Amps @ 28V for HDS Signal ckt |
| 60 Amps @ 600V for power ckt | 50 Amps at 60V for power ckt |

2.4.2 UL - IEC61984 EU- Certificate Number: UL-EU-01060-A1



UL-CB - Report – E29179 -D1-CB IEC 61984-1 Non-current interruption 7.5 mm Pitch 600 volts AC/DC @ 60 amps 5.5 mm Pitch 250 volts DC @ 60 amps Signal Signal Legacy (3 row) 120 Volts AC/DC @ 60 amps Signal HDS (5 row) 120 Volts AC/DC @ 1.0 amps IEC 61984 Certification: Tested to and found in compliance with IEC 61984. Certificate available from Molex upon request. Contact Molex safety agency team for questions regarding certification on specific part numbers.

2.4.3 UL File Number: E29179

| UL NON-current interruption |
|-------------------------------------------------------------------------------------------------------------|
| 2.5 Amps @ 250V for Legacy signal ckt 4.5 Amps @ 120V for HDS signal ckt 80 Amps @ 600V for power ckt |

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| TEMPLATE FILE | VAME: 1703070003 REV A | | | | | | |

3.0 APPLICABLE DOCUMENTS AND SPECIFICATION

3.1 MOLEX DOCUMENTS

molex

Extreme Ten60Power Connector System Application summary AS-4636-100-001 Molex Solderability Specification SMES-152 Molex Heat Resistance Specification AS-40000-5013 Molex Moisture Technical Advisory AS-45499-001 Molex Package Handling Specification 454990100-PK ATS – Application Tooling Specification*

*Application Tooling Specification for terminals is not provided in this document. ATS for terminals can be available from respective terminal part number page in Molex.com

3.2 INDUSTRY DOCUMENTS

EIA-364-1000 UL-60950-1 CSA STD. C22.2 NO. 182.3-M1987 IEC 61984 UL-1977

4.0 ELECTRICAL PERFORMANCE RATINGS

4.1 VOLTAGE

Legacy Signal Module: HDS Signal Module: Power Module: 250 Volts120 Volts250 or 600 Volts (Ref. to pads layout in section 7.2)

Connector Rating per UL-1977

Connector voltage rating meets the connector approval level defined by UL 1977, Sect. 11 for spacing per table 11.1. Example: 1.2 mm for \leq 250 volt; 3.2 mm for \geq 250 volt.

Exception taken for spacing less than those specified are permitted, if the device complies with the requirements in the dielectric voltage withstanding test per Sect. 17

Application Voltage Guideline

For application voltage requirements please refer to UL-60950 or other applicable standards, the creepage & clearance also needs to be determined based upon pads/traces on the PCB.

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| PS | 5-46436-100 | PS | <u>001</u> | ABHIRK | SUVARS | HTHYA | GARAJ |
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PRODUCT SPECIFICATION molex

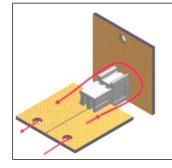
4.2 **CURRENT RATING (MAXIMUM AMPERES)**

Signal Contact: HDS Signal Contact: Power Contact:

2.5 Amps

4.5 Amps

- 1. Tested with PCB Copper Planes: See charts on page 10.

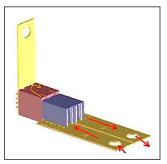


| No. of Power Circuits | 1-Ckt | 2-Ckt | 4-Ckt | 8-Ckt |
|-----------------------|--------|--------|--------|--------|
| Current (Amps) | 94Amps | 85Amps | 76Amps | 65Amps |

** Tested in accordance with EIA-364-70. Refer section 6.1.5

The above current ratings are based on testing connectors are mounted to a 10-Layer PCB with 2Oz per layer copper planes. Rating shown represents maximum current carrying capacity at 30°C temperature rise over ambient temperature.

2. Tested with Copper Coupons: See charts on page 11.



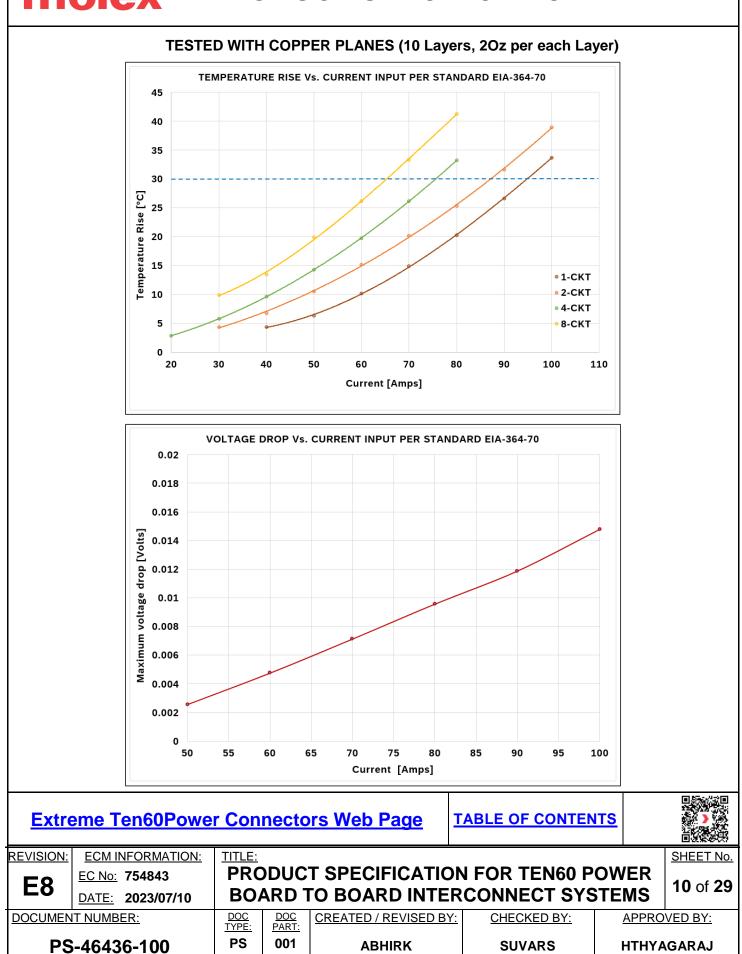
| No. of Power Contacts | 1-Ckt | 2-Ckt | 4-Ckt | 8-Ckt |
|-----------------------|--------|--------|--------|--------|
| Current (Amps) | 62Amps | 59Amps | 57Amps | 53Amps |

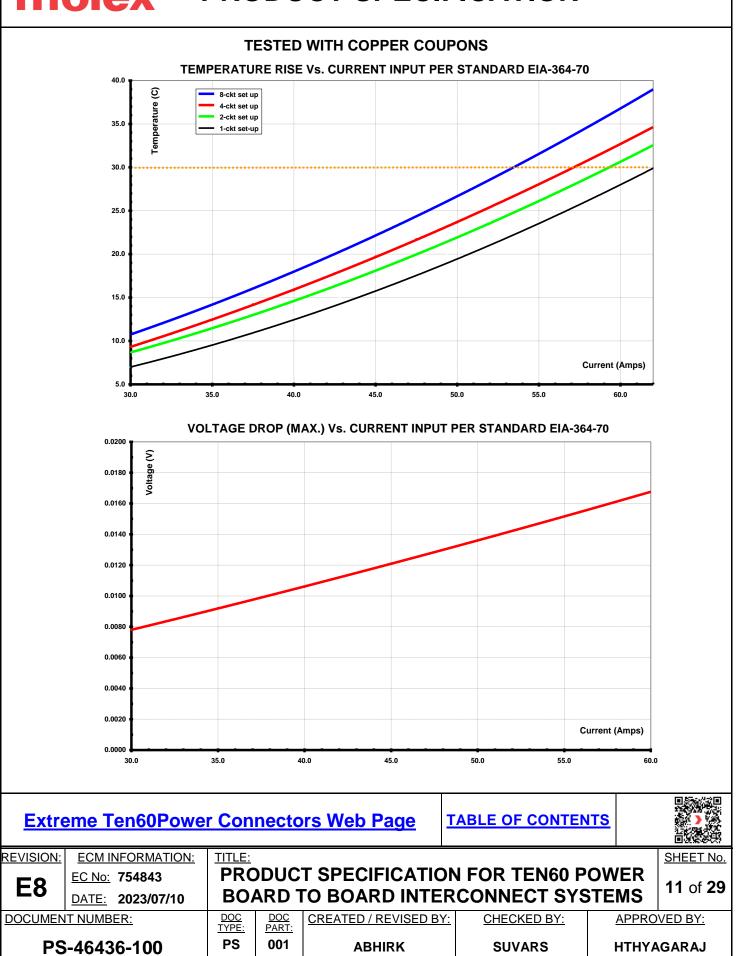
**Tested in accordance with EIA-364-70. Refer section 6.1.5

The above current ratings are based on testing connectors are mounted on a copper coupon. Rating shown represents maximum current carrying capacity at 30°C temperature rise over ambient temperature.

"Current rating is application dependent and should be used as a guideline. Appropriate rating is required per ckt size, ambient conditions, copper trace size on the PCB, gross heating from adjacent modules/components and other factors that influence connector performance"

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4.3 TEMPERATURE

molex

Operating temperature (including T-rise from applied current) is -40° C to +105° C.

Temperature life tested per EIA 364-17 Method A for 240 hrs@105° per table 8 to meet field temperature of 65° C for 10 years life. See page 22 for detail test sequence of EIA-364-1000, Group I.

4.4 DURABILITY

| Plating Type | Number of Cycles |
|--------------|------------------|
| Gold Plated | 200 |

As tested in accordance with EIA-364-1000 test method C section 7 (see sec 6.2.3 of this specification). Durability per EIA-364-09

5.0 QUALIFICATION

Laboratory condition, sample selection and test sequences are in accordance with EIA-364-1000.

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6.0 PERFORMANCE

6.1 ELECTRICAL PERFORMANCE

| ITEM | DESCRIPTION | TEST CONDITION | REQUIREMENT |
|-------|----------------------------------------------|----------------------------------------------------------------------------------------|--------------------------------------------------------------------|
| 6.1.1 | Initial Contact Resistance (Low Level) | Per EIA-364-23 | Signal Contact: 30 m Ω Power Contact: 0.3 m Ω |
| 6.1.2 | Voltage Drop (@ Rated Current) | Mate connectors; apply the rated current. Per EIA-364-70 | Typical Voltage Drop: Power Contact: see chart, Page 10 & 11 |
| 6.1.3 | Insulation Resistance | Apply 500 VDC between adjacent terminals or ground. Per EIA-364-21 | 5,000 MΩ minimum |
| 6.1.4 | Dielectric Withstanding Voltage | Apply 1500 VDC for 1 minute between adjacent terminals or ground. Per EIA-364-20 | No breakdown |
| 6.1.5 | Temperature Rise | Mate connectors Measure T-Rise @ Rated Current After 96 Hours. Per EIA-364-70 | 30°C T-Rise |

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6.2 **MECHANICAL PERFORMANCE**

| | M DESCRIP | TION | | TEST CONDITION | | REQUI | REMENT |
|----------------------------------------------|-----------------------------|-------------|-----------------------------|---------------------------------------------------------------------|----------------|-------------------------------------------------------|------------------------------------------------------------|
| | | | | | | | y Signal ckt Max |
| 6.2. | 1 Mating Fo | | | te connectors at a rate 25.4±6 mm per minute Per EIA-364-37 | of | Power Vert Recept to R/A Plug 756 g/ckt Max | Power R/A Recept to R/A Plug 443 g/ckt Max |
| | | | | | | | DS* ckt Max |
| | | | | | | | y Signal ckt Min |
| 6.2. | 2 Unmating F Single Cire | | | nate connectors at a ra 25.4±6 mm per minute Per EIA-364-37 | | Power Vert Receipt to R/A Plug 316 g/ckt Min | Power R/A Recept to R/A Plug 253 g/ckt Min |
| | | | | | | | DS* per Contact |
| 6.2. | 3 Durability Environn | | | e connectors 20 cycles rate of 10 cycles per m Per EIA-364-09 | | Signal Cor | n Change: htact: 10 m Ω cact: 0.30 m Ω |
| | | | | | | | Power 5 g Min |
| 6.2. | 4 Contac | | | pullout force on the ter ousing at a rate of 25.4 | | | |
| | Retentio | on | | er minute Per EIA-364-2 | | | S Signals per coupon |
| | | | | | | | S Signals per coupon |
| | HDS: High Dens | | | | | | |
| ** | Mate/Unmate D | Data is for | 1st Cycle | e | | | |
| ** •eme 1 | Mate/Unmate D | Pata is for | 1st Cycle | | TABLE | OF CONTENT | |
| ** reme 1 <u>ECMI</u> <u>EC No:</u> | Mate/Unmate D | er Coni | 1st Cycle | • <u>'s Web Page</u> ' SPECIFICATIC | ON FOI | R TEN60 PC | OWER |
| ** eme 1 : ECMI EC No: | Mate/Unmate D | er Coni | 1st Cycle nector DUCT | e : <mark>s Web Page</mark> | ON FOI RCON | R TEN60 PC | OWER |

molex PRODUCT SPECIFICATION

6.2 **MECHANICAL PERFORMANCE CONTINUED**

| | ITEM | DESCRIPTION | | TEST CONDITION | | | QUIREMENT | | |
|-----------------|----------------------------------------------------------------------------|-------------------------------------------------------------------------|--------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------|----------|-------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------|--|--|
| | Min Extraction | | Dull out contacto et o rote of | | | MIN: 1.10 lbs. (0.5 Kg/pin) (Legacy Signal Module) MIN: 1.00 lbs. (0.45 Kg/pin) (HDS Module) | | | |
| | 6.2.5 | force for Terminals with Compliant Pins | | | | MIN: 2.37 lbs./pin (1.08 Kg/pin) Vertical Power Receptacle MIN: 2.4 lbs./pin (1.09 Kg/pin) | | | |
| | | | | | | | A Power Plug | | |
| | 6.2.6Vibration (EIA-364-1000)6.2.7Mechanical Shock (EIA-364-1000) | | | 00) EIA-364-28 test condition VII-D 15 minutes each axis. al Mate connectors and shock at 50 g with ½ sine wave (11 milliseconds) shocks in the | | | imum Change: Contact: 10 mΩ Contact: 0.50 mΩ | | |
| | | | | | | | imum Change: Contact: 10 mΩ Contact: 0.50 mΩ | | |
| | | | | | | | MAX: 12.54 lbs/pin (5.7 Kg/ckt) (Legacy Signal Module) MAX: 10.02 lbs/pin | | |
| | 6.2.8 | Max Insertion force into PCB for Terminals with Compliant Pins | 25.4±6 mm per minute | | | (4.54 kg/ckt) (HDS module) MAX: 18.5 lbs/pin (8.41 kg/pin) | | | |
| | | Compliant 1 ins | | | | | (Vertical Pwr Receptacle) MAX: 17.6 lbs/pin (7.98 kg/pin) | | |
| | | | | | | | /A Pwr Plug) | | |
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| PS | -46436- | •100 PS | <u>PART:</u> 001 | ABHIRK | SUVA | | | | |
| I EMPLATE FILE | NAME: 170307000 | IS REV A | | 1 | <u> </u> | | L | | |

6.3 ENVIRONMENTAL PERFORMANCE

| ITEM | DESCRIPTION | TEST CONDITION | REQUIREMENT | |
|-------|-------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------|--|
| 6.3.1 | Thermal Shock (EIA-364-1000) | Mate connectors, expose to 10 cycles from -55°C to 85°C Per EIA-364-32 | Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω | |
| 6.3.2 | Temperature Life (EIA-364-1000) | Mate Connectors, expose to 240 hours at 105°C Per EIA-364-17 | Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω | |
| 6.3.3 | Cyclic Temperature and Humidity (EIA-364-1000) | Mate connectors: expose to 24 cycles from 25 °C / 80% RH to 65 °C / 50% RH Per EIA-364-31 | Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω | |
| 6.3.4 | Dust (EIA-364-1000) | Un-mated 1-hour duration 25°C/50% RH dust mass of 9 g/ft ³ at rate of 300 m/min. Per EIA-364-91 | Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω | |
| 6.3.5 | Mixed Flowing Gas (EIA-364-1000) | 168 hours un-mated,168 hours mated, Per EIA-364-65Class II-A | Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω | |
| 6.3.6 | Solderability Dip Test | Molex test method: | Solder area shell have Min o 95% solder coverage | |
| 6.3.7 | Compliant pin retention force from PCB board after soldering process | Per EIA-364-61, Test procedure 4 for compliant pin retention force | 22.5 lbs. (10.2 Kg) Per Power contact extraction force from PCB | |
| 6.3.8 | Resistance to soldering heat from rework | Per EIA-364-61, Test procedure 2 (Test Condition II) | No dimensions change No physical damage | |

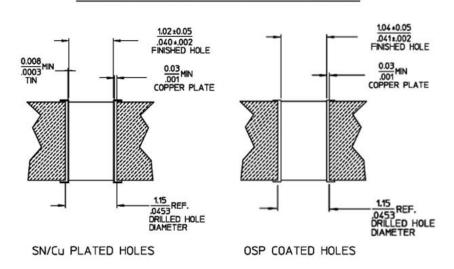
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| REVISION: | REVISION: ECM INFORMATION: TITLE: | | | | | | SHEET No. | | |
| E8 | EC No: 754843 | PRC | PRODUCT SPECIFICATION FOR TEN60 POWER | | | | | | |
| | DATE: 2023/07/10 | BO | BOARD TO BOARD INTERCONNECT SYSTEMS | | | | | | |
| DOCUMEN | DOCUMENT NUMBER: | | | CREATED / REVISED BY | (: <u>CHECKED BY:</u> | APPRO | VED BY: | | |
| PS | <u>TYPE:</u> PS | <u>PART:</u> 001 | ABHIRK | SUVARS | HTHY | GARAJ | | | |
| TEMPLATE FILE | NAME: 1703070003 REV A | | | | | | | | |

7.0 PRINTED CIRCUIT BOARD SPECIFICATION

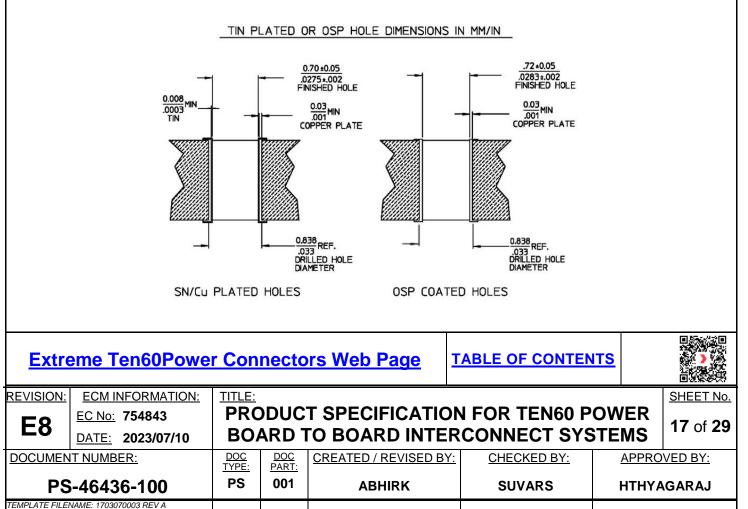
7.1 PCB THROUGH HOLE SPEC.

Profile for 1.02 mm (finish) holes:

TIN PLATED OR OSP HOLE DIMENSIONS IN MM/IN



Profile for 0.70mm (finish) holes - Signal segment:



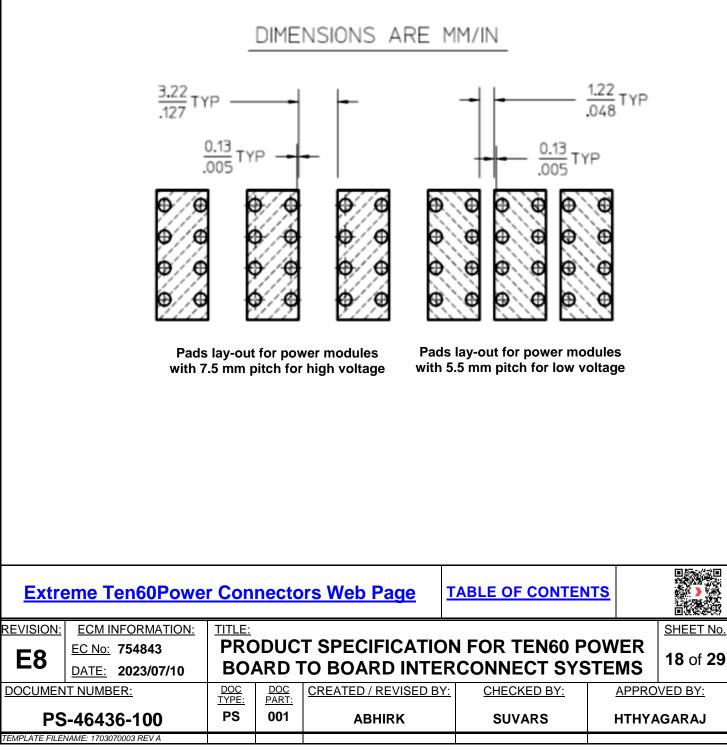
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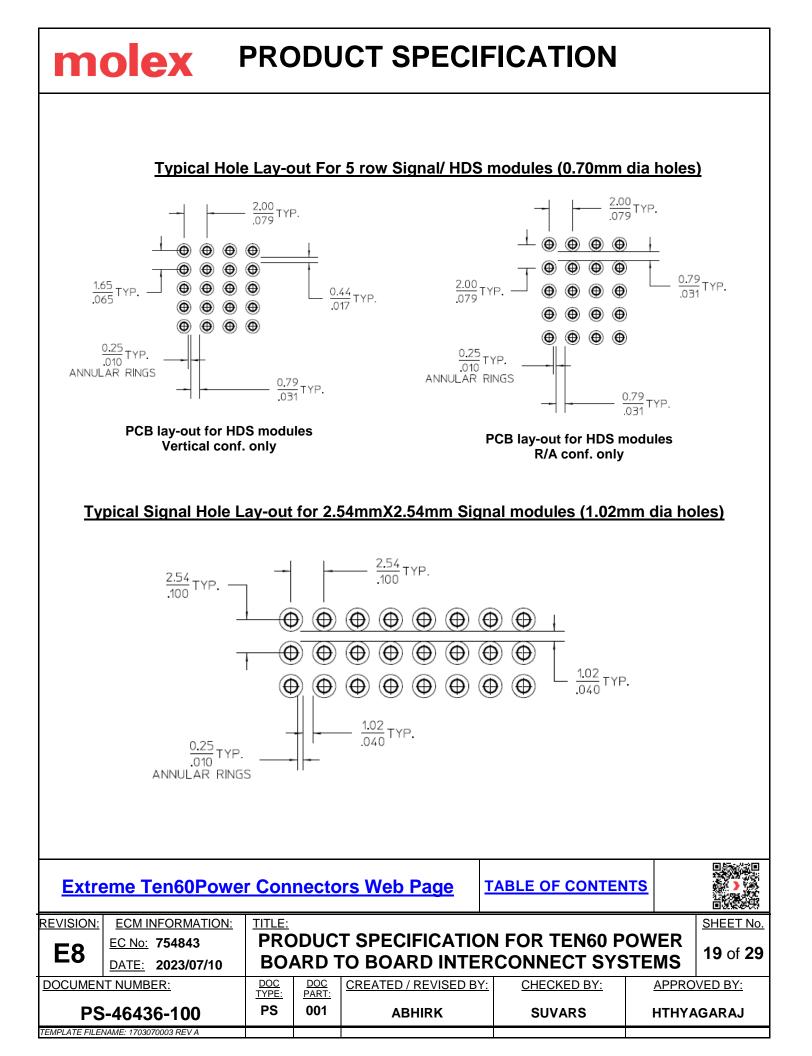
PRODUCT SPECIFICATION

Notes:

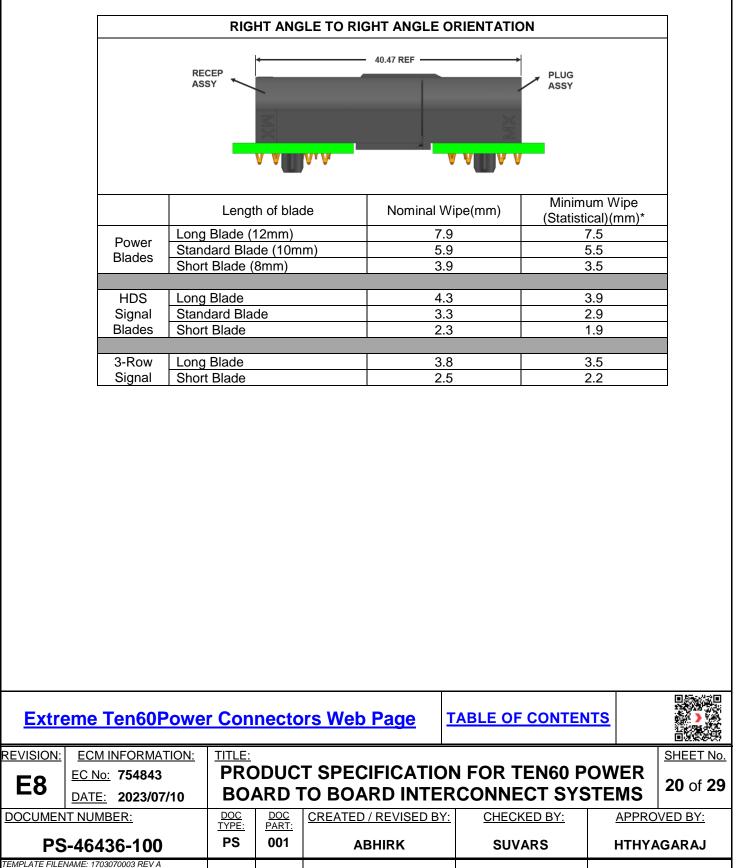
- 1. The finished hole size is the critical feature for proper performance of the compliant pin terminal. The reference drill sizes listed are recommended by Molex to achieve the finished PCB hole size.
- 2. Depending on the specific manufacturer's plating process a different drill size can be used to achieve the required finished PCB hole size.

7.2 TYPICAL PCB PADS LAY-OUT AND SIGNAL HOLES LAY-OUT





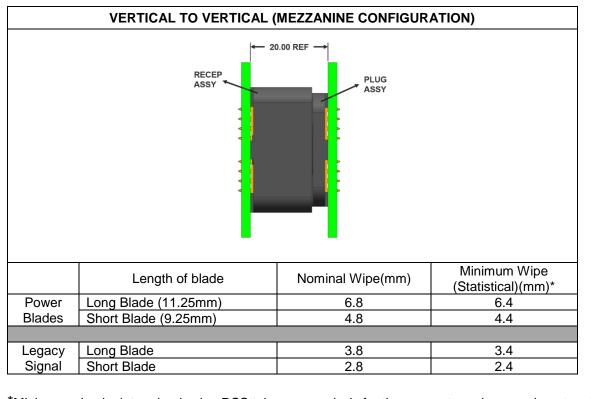
7.3 WIPE LENGTH DETAILS



| | | RIGHT A | NGLE TO VERTICAL OF | | | | | |
|--------------------|-----------------------------------------------|------------------------------------------|----------------------|--------------------|-------------------------|--|--|--|
| | RECEP ASSY PLUG ASSY VVVV VVVV | | | | | | | |
| | | Length of bla | de Nominal V | | num Wipe tical)(mm)* | | | |
| | Power | Long Blade (12mm) | 6. | 8 | 6.4 | | | |
| | Blades | Standard Blade (10m Short Blade (8mm) | 1m) 4. 2. | | <u>4.4</u> 2.4 | | | |
| | | | | | | | | |
| | HDS Signal | Long Blade Standard Blade | 4. | | 3.9 2.9 | | | |
| | Blades | Short Blade | 2. | | 1.9 | | | |
| | 3-Row | Long Blade | 3. | 7 | 3.4 | | | |
| | Signal | Short Blade | 2. | | 2.1 | | | |
| | | | | | | | | |
| Extre REVISION: | 1 | | ors Web Page | TABLE OF CONTEI | SHEET No. | | | |
| E8 | EC No: 754843 DATE: 2023/07 | | T SPECIFICATIO | | 21 of 20 | | | |
| DOCUMEN | IT NUMBER: | DOC DOC TYPE: PART: | CREATED / REVISED BY | <u>CHECKED BY:</u> | APPROVED BY: | | | |
| | -46436-100 | PS 001 | ABHIRK | SUVARS | HTHYAGARAJ | | | |
| TEMPLATE FILE | NAME: 1703070003 REV A | | | | | | | |

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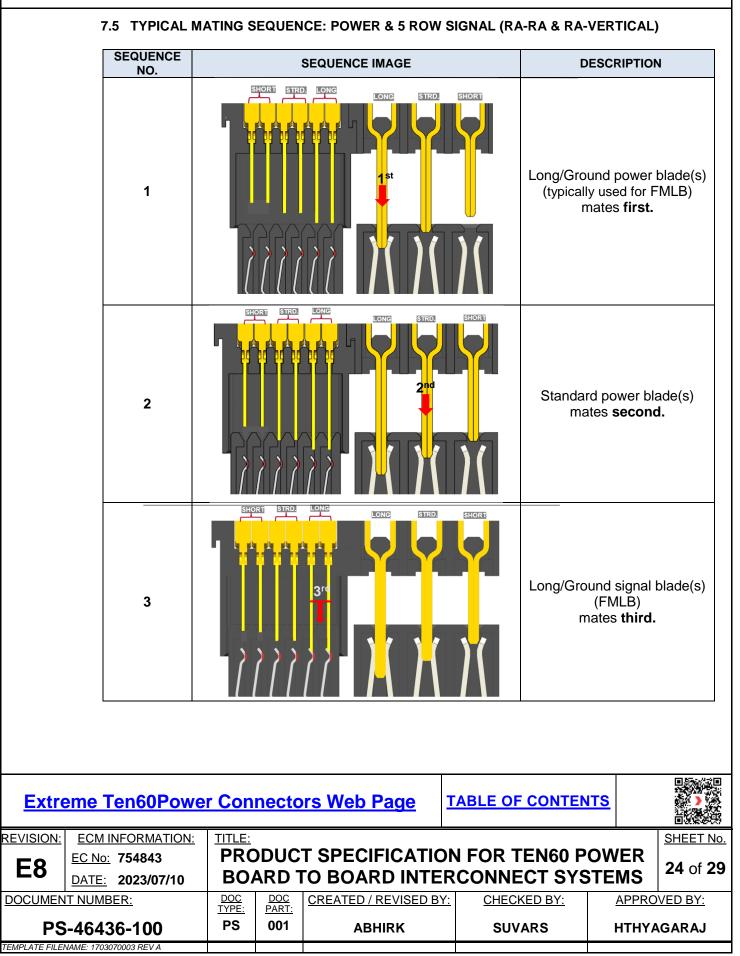
PRODUCT SPECIFICATION

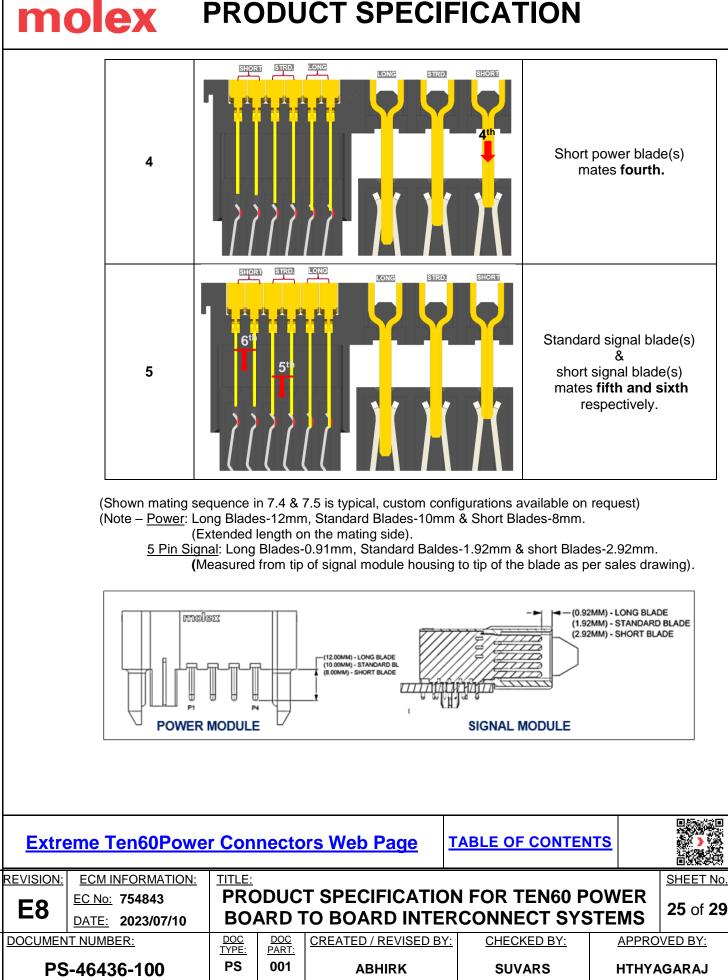


*Minimum wipe is determined using RSS tolerance analysis for the connector only assuming at mated condition as per reference mating length provided in the illustration above. Mated profile tolerances and system tolerances are not considered into the analysis

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|-----------------------------------|-----------------------------------------------------------------------------------------------------|-------------------|--------------|----------------------|---------------|--------|-----------|
| REVISION: ECM INFORMATION: TITLE: | | | | | | | SHEET No. |
| E8 | EC No:754843PRODUCT SPECIFICATION FOR TEN60 POWERDATE:2023/07/10BOARD TO BOARD INTERCONNECT SYSTEMS | | | | | | |
| DOCUMEN | DOCUMENT NUMBER: | | DOC PART: | CREATED / REVISED BY | : CHECKED BY: | APPRC | VED BY: |
| PS | <u>TYPE:</u> PS | 001 | ABHIRK | SUVARS | нтнү | AGARAJ | |
| TEMPLATE FILE | | | | | | | |

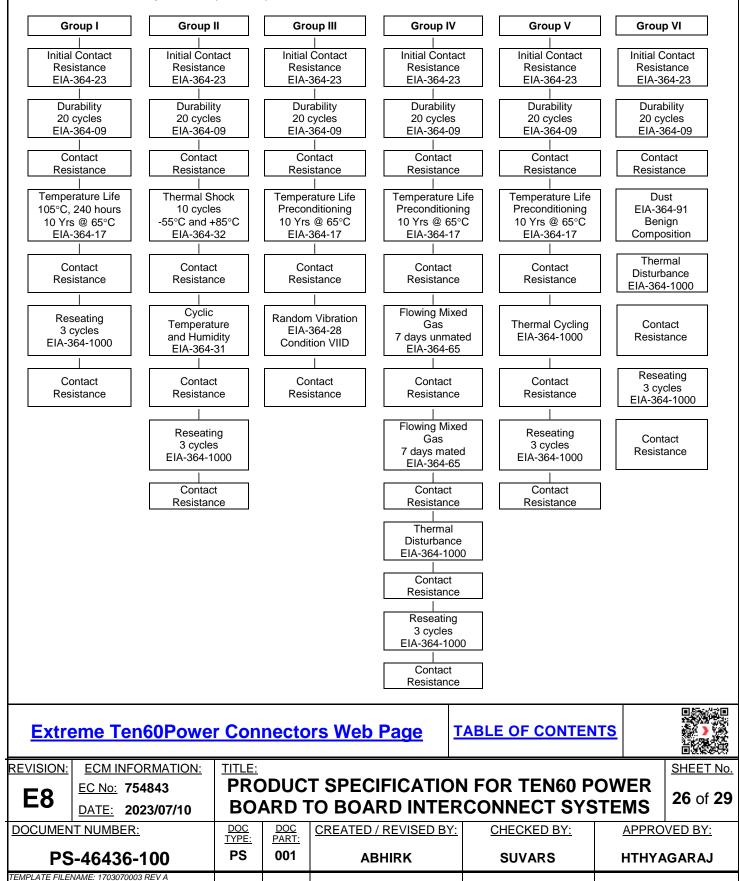
| | SEQUENCE NO. | SEC | QUENCE IMAGE | DESCR | RIPTION | | |
|-------------|---------------------------------------------------------|------------------------|-----------------------|----------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|--|
| | 1 | | | (typically use | Long/Ground power blade(s) (typically used for FMLB) mates first. Short power blade(s) mates second. 3. After short power blade(s) the long signal pins (typically the top row) mates third. 4. After long signal pins, the rest of other signal pins will mate. | | |
| | 2 | | | | | | |
| | 3 & 4 | | | long signal pins row) mat 4. After long sign | | | |
| Extreme | Ten60Powe | er Connecto | ors Web Page | ABLE OF CONTEN | | | |
| | INFORMATION: <u>5:</u> 754843 <u>:</u> 2023/07/10 | | T SPECIFICATION | | 22 of | | |
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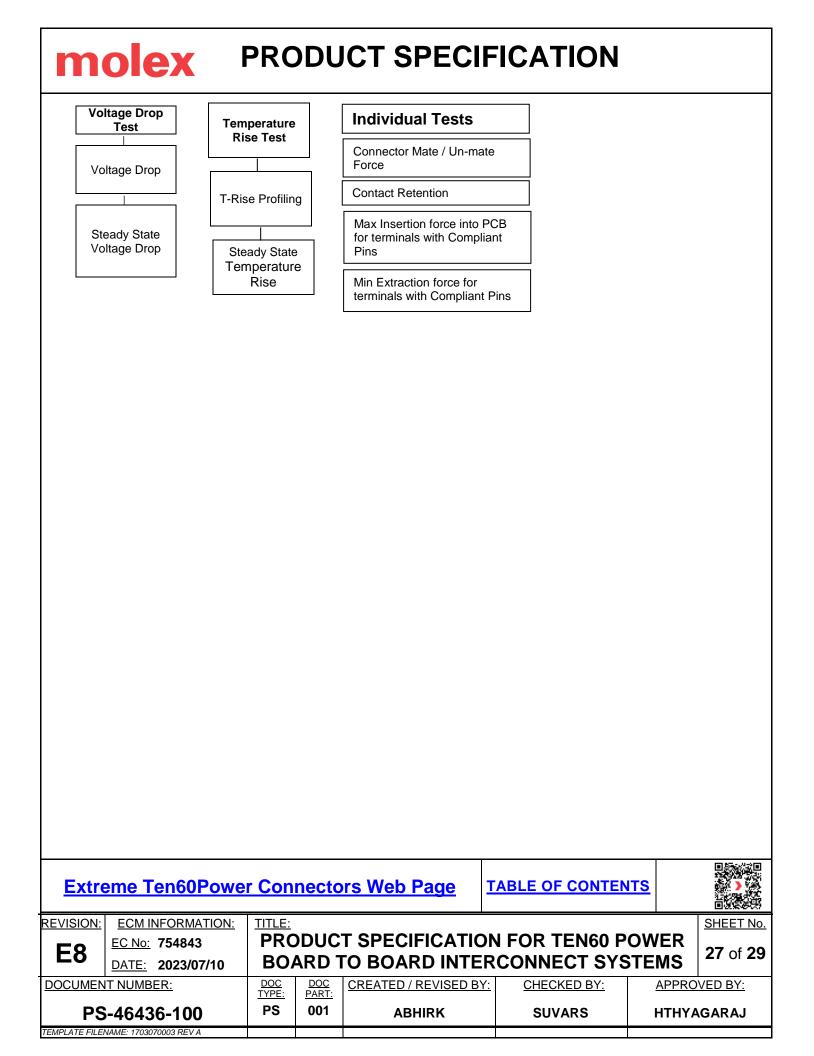




8.0 TEST SEQUENCE GROUPS

Reliability Test Sequences per EIA-364-1000





molex SOLDER INFORMATION 9.0 Per SMES-152 and AS-40000-5013 *These specifications establish standard solderability test methods used to evaluate a products ability to accept molten solder. Solder Process Temperatures and Reflow Solder Profiles will vary based on application, equipment, solder paste, PCB thickness, etc. 9.1 **SOLDER PROCESS TEMPERATURES *** Molex Solderability Specification **SMES-152** Reflow Solder Temperature: 260°C Maximum (Click Here) 9.2 SOLDERING PROFILE (This profile is per JEDEC J-STD-020D.1 and it is for guideline only; please see notes for additional information) Molex Connector Heat Resistance Specification AS-40000-5013 (Click Here) Time to Peak Temperature Time at Peak Temperature Ramp Rate Temperature Ramp Rate Temperature Preheat Temperature Ramp Rate **Fime at Preheat Temperature** Cool Down Peak Peak Temperature Liquidus Temperature Preheat Temperature Time Within 5 °C ofPeak Room Temperature Time Time Above Liquidus Temperature Extreme Ten60Power Connectors Web Page **TABLE OF CONTENTS** SHEET No. **REVISION**: **ECM INFORMATION:** TITLE: **PRODUCT SPECIFICATION FOR TEN60 POWER** EC No: 754843 **E8** 28 of 29 **BOARD TO BOARD INTERCONNECT SYSTEMS** DATE: 2023/07/10 DOC TYPE: DOC PART: DOCUMENT NUMBER: CREATED / REVISED BY: CHECKED BY: APPROVED BY: PS 001 SUVARS **HTHYAGARAJ** PS-46436-100 ABHIRK

| Description | Requirement | | | |
|---------------------------|------------------------|--|--|--|
| Average Ramp Rate | 3°C/sec Max | | | |
| Preheat Temperature | 150°C Min to 200°C Max | | | |
| Preheat Time | 60 to 180 sec | | | |
| Ramp to Peak | 3°C/sec Max | | | |
| Time over Liquids (217°C) | 60 to 150 sec | | | |
| Peak Temperature | 260 +0/-5°C | | | |
| Time within 5°C of Peak | 20 to 40 sec | | | |
| Ramp - Cool Down | 6°C/sec Max | | | |
| Time 25°C to Peak | 8 min Max | | | |

Notes:

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- 1. Temperature indicated refers to the PCB surface temperature at solder tail area.
- 2. Connector can withstand up to 3 reflow cycles with a cool-down to room temperature in-between.
- Actual reflow profile also depends on equipment, solder paste, PCB thickness, and other components on the board. Please consult your solder paste & reflow equipment manufacturer for their recommendations to adopt a suitable process.

10.0 PACKAGING

Parts shall be packaging to protect the parts from damage during standard shipping, storage, and handling. Refer Molex.com specific part number webpage to get the exact packaging document for that item.

| | Extreme Ten60Power Connectors Web Page TABLE OF CONTENTS | | | | | | | | |
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| R | EVISION: | ECM INFORMATION: | TITLE: | | | | | SHEET No. | |
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| | PS-46436-100 | | | 001 | ABHIRK | SUVARS | HTHYA | GARAJ | |
| TE | TEMPLATE FILENAME: 1703070003 REV A | | | | | | | | |